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Prajuckamol et al.

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(54) **POWER DEVICE PACKAGE**

(71) Applicant: **Semiconductor Components Industries, LLC**, Phoenix, AZ (US)

(72) Inventors: **Atapol Prajuckamol**, Klaeng (TH); **Chee Hiong Chew**, Seremban (MY); **Yushuang Yao**, Seremban (MY)

(73) Assignee: **SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC**, Phoenix, AZ (US)

(**) Term: **14 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 361/772, 775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/428; G02B 6/4281; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026
See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki

(57) **CLAIM**

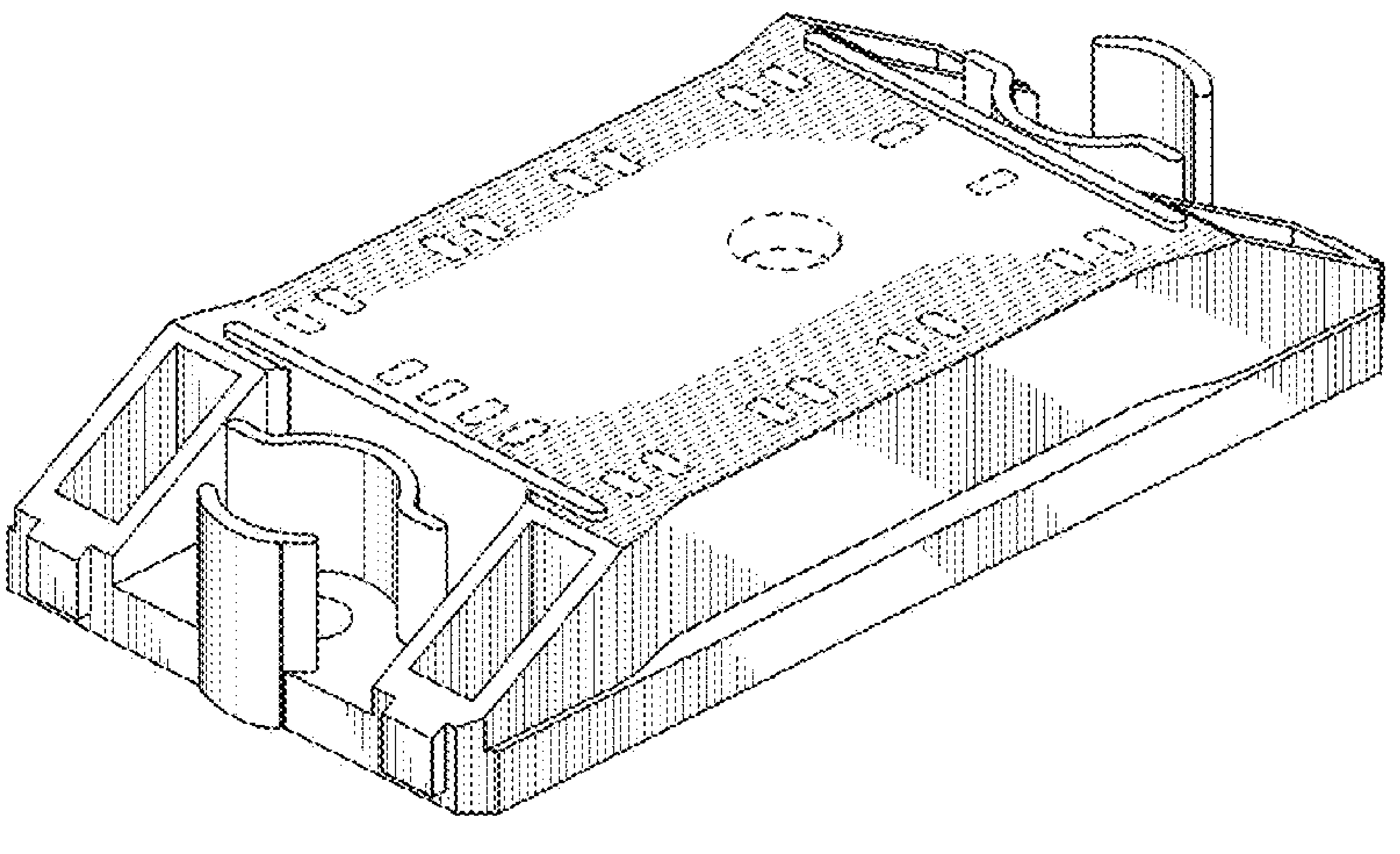
The ornamental design for a power device package, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a power device package showing my new design;
FIG. **2** is another top perspective view thereof;
FIG. **3** is a bottom perspective view thereof;
FIG. **4** is a top plan view thereof;
FIG. **5** is a bottom plan view thereof;
FIG. **6** is a left side elevation view thereof;
FIG. **7** is a right side elevation view thereof;
FIG. **8** is a back elevation view thereof; and,
FIG. **9** is a front elevation view thereof.

The broken lines shown in the drawings represent portions of the power device package that form no part of the claimed design.

1 Claim, 4 Drawing Sheets



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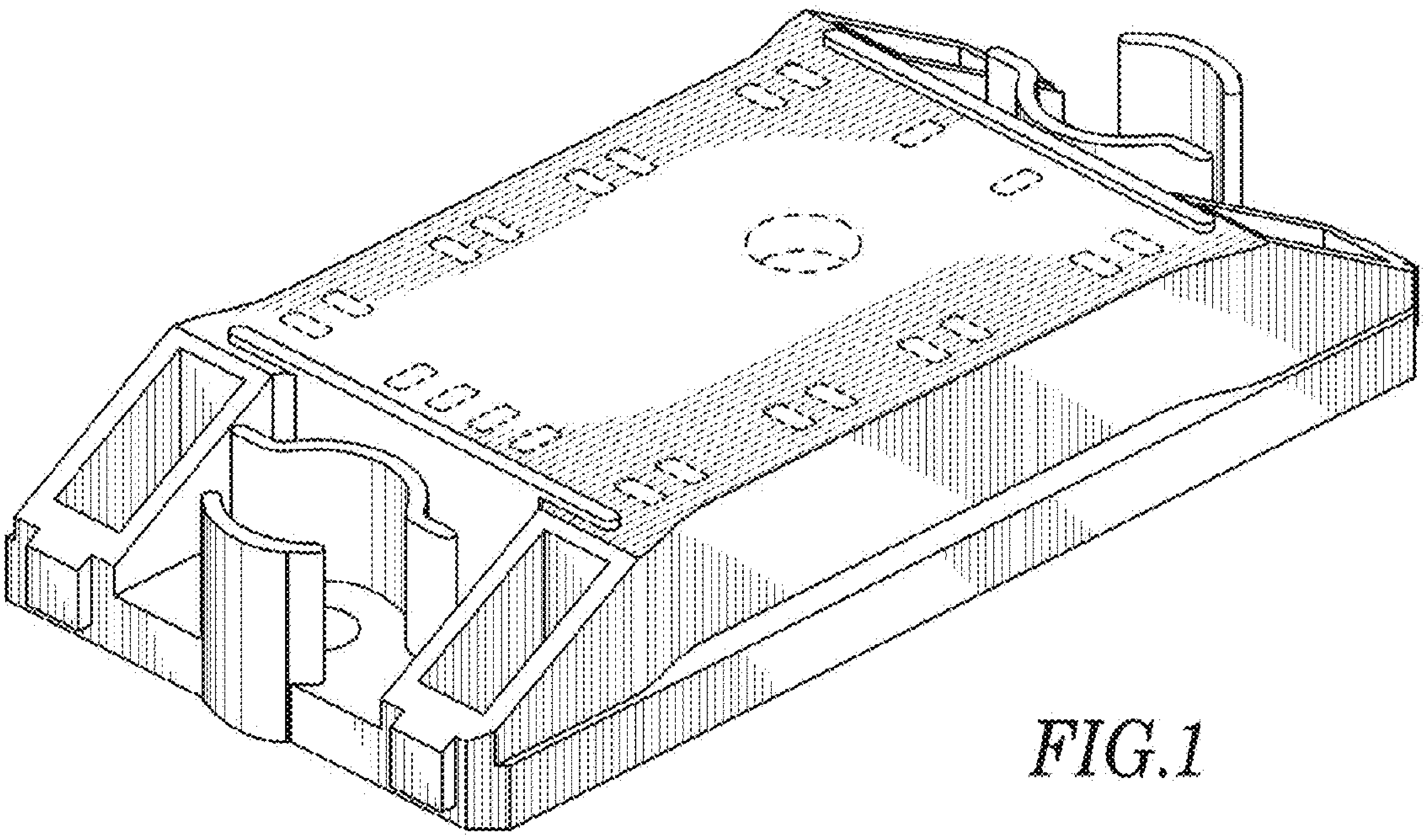

FIG.1

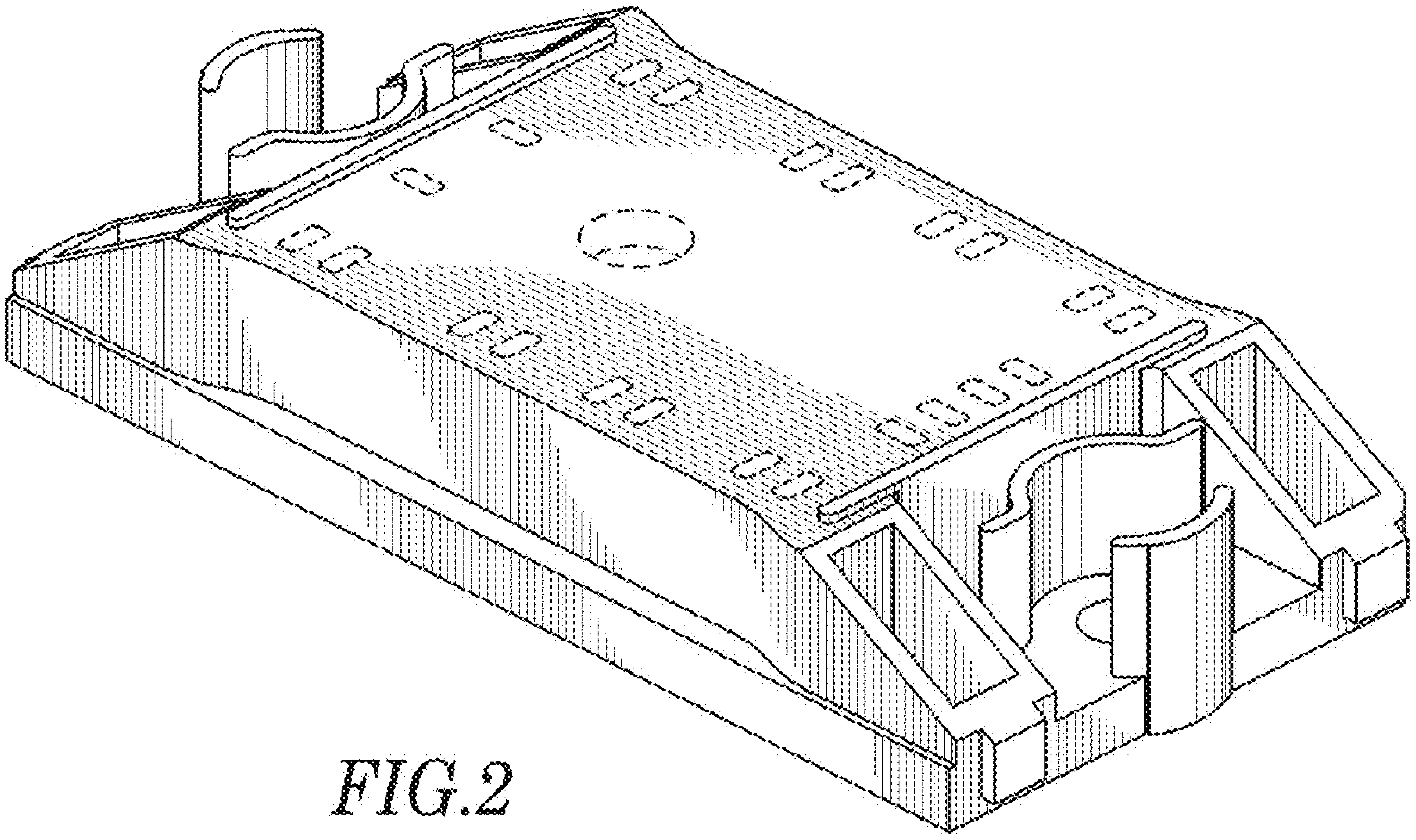

FIG.2

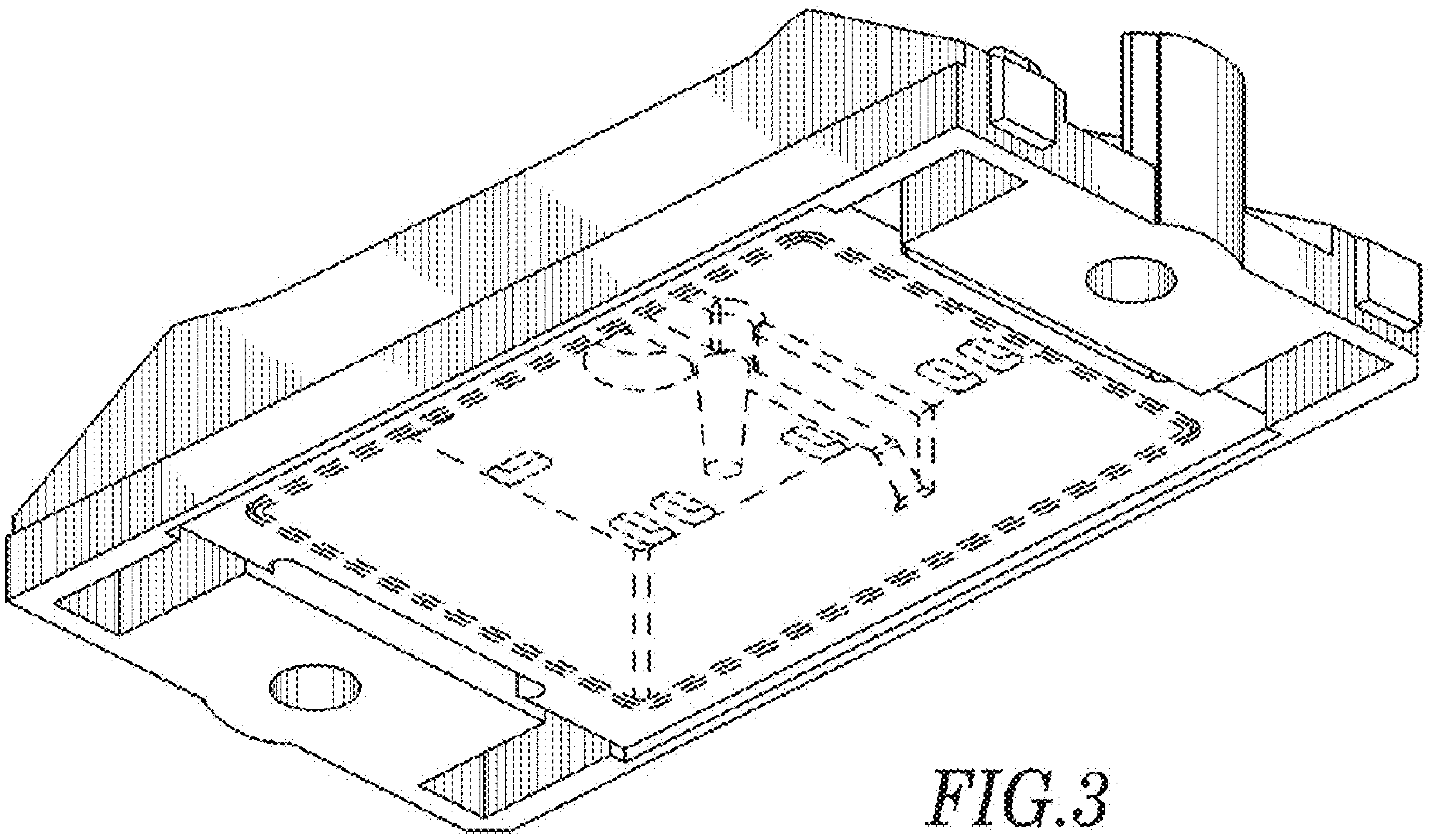

FIG.3

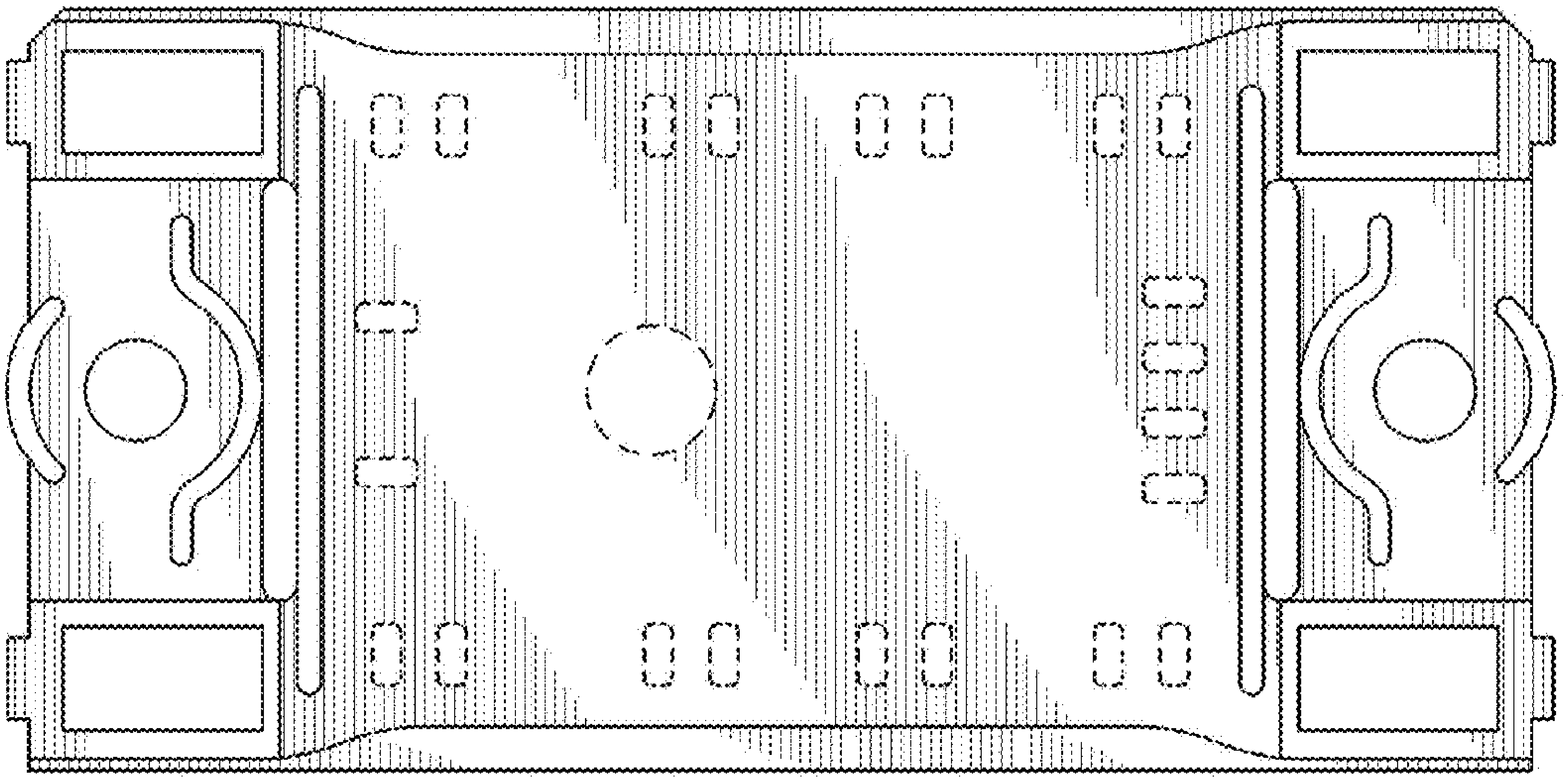

FIG.4

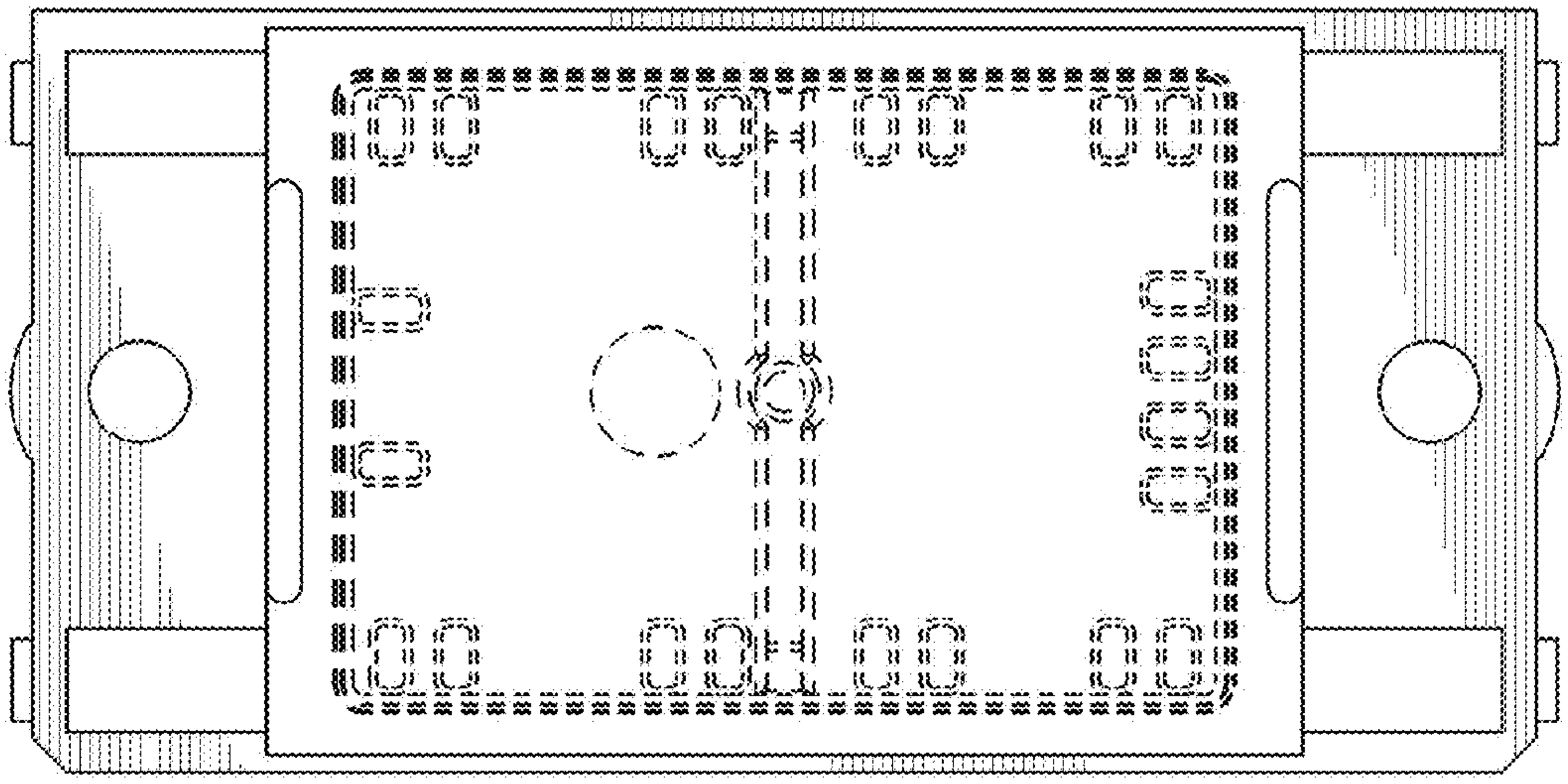

FIG.5

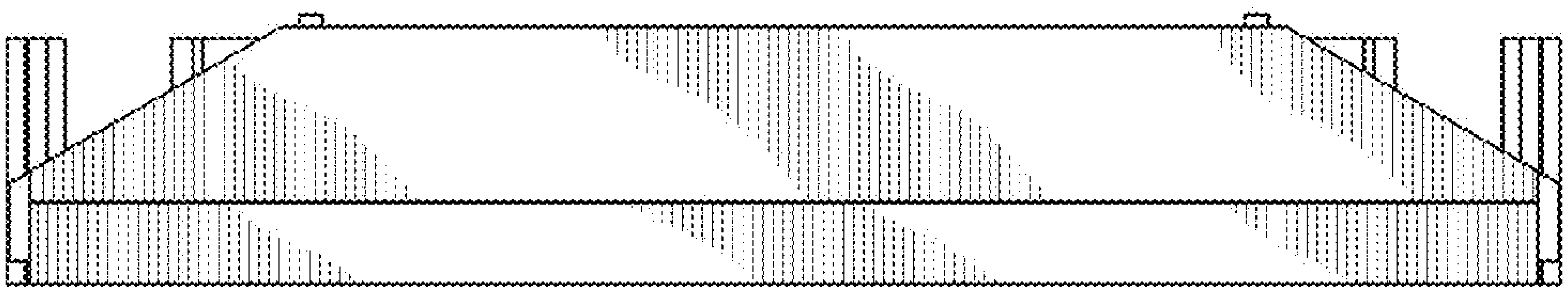

FIG.6

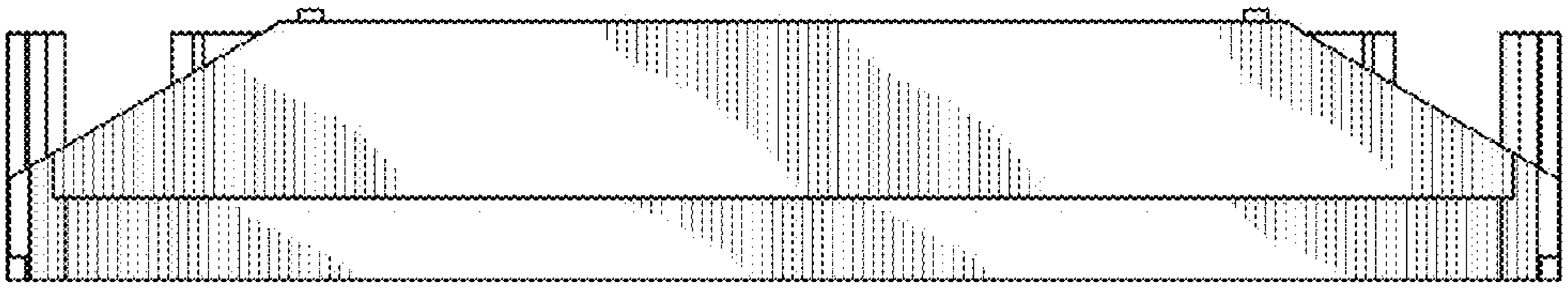

FIG.7

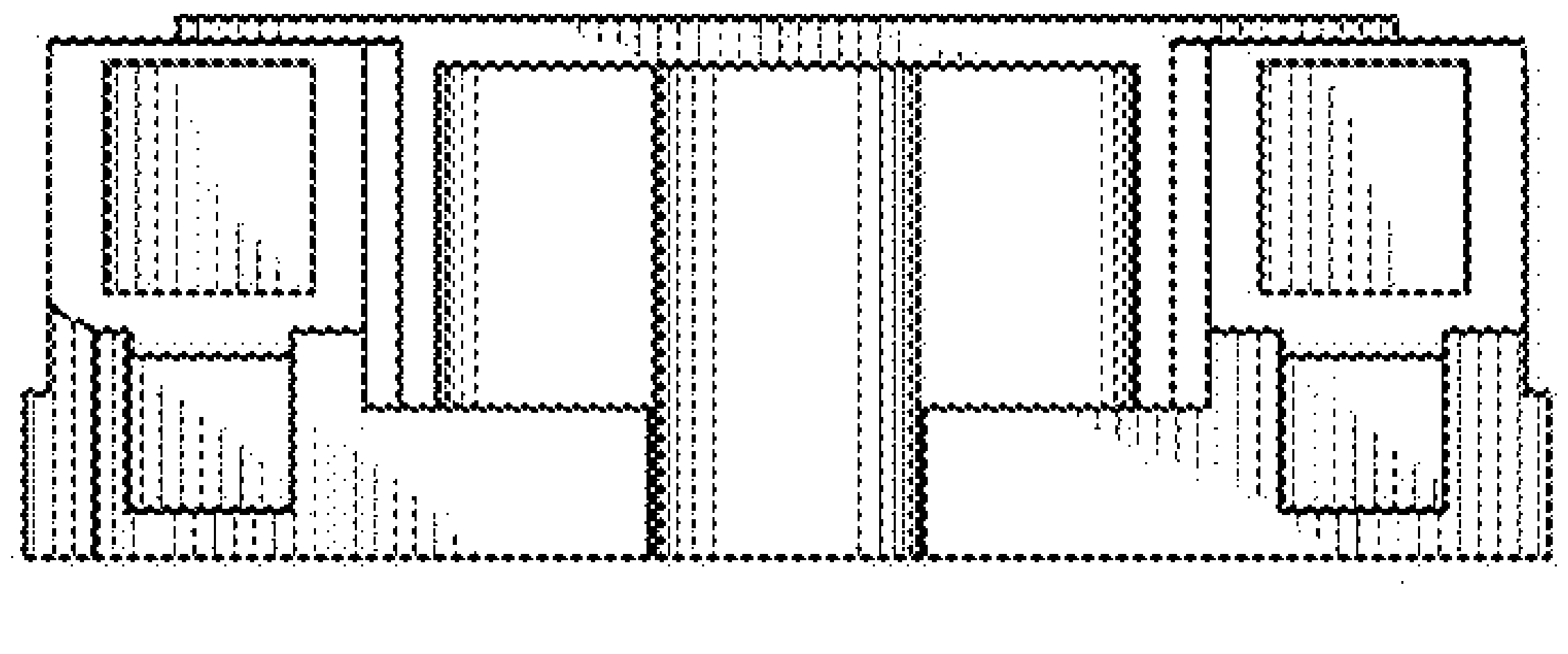

FIG.8

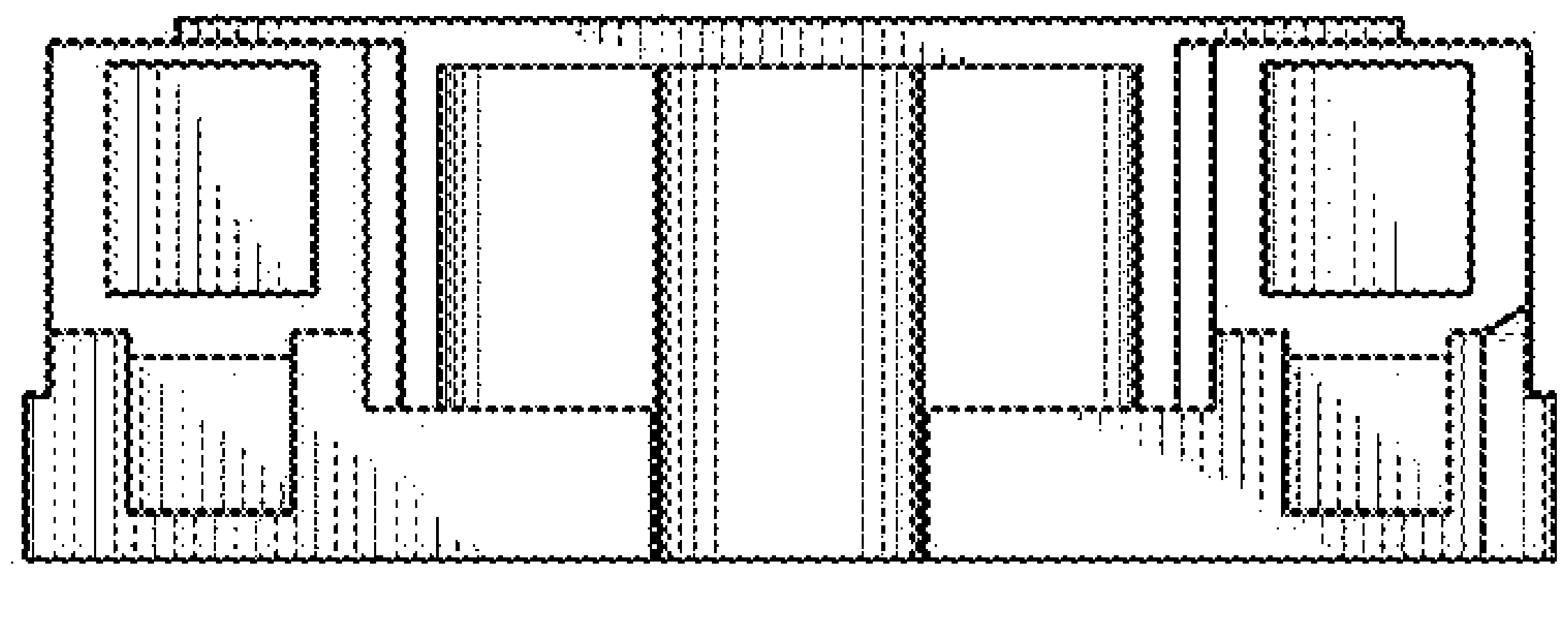

FIG.9